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(12) **United States Design Patent** (10) **Patent No.:** **US D515,043 S**  
**Ishizaka et al.** (45) **Date of Patent:** **\*\* Feb. 14, 2006**

(54) **LIGHT EMITTING DIODE**

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(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.** ..... **D13/180**

(58) **Field of Classification Search** ..... D13/180;  
D26/2; 257/79, 80, 81, 82, 88, 89, 95, 98,  
257/99, 100, 433, 434, 666; 313/483, 498,  
313/500; 361/820; 362/235, 555, 800; 372/45  
See application file for complete search history.

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PLLC

(57) **CLAIM**

The ornamental design for the light emitting diode, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of the light emitting diode, FIG. 2 is a front view thereof the rear view being a mirror image,  
FIG. 3 is a plan view thereof,  
FIG. 4 is a bottom view thereof,  
FIG. 5 is a right side view, the left side view being a mirror image thereof; and,  
FIG. 6 is a perspective view thereof as viewed from below. This item is a light emitting diode, wherein a reflecting frame is provided on an upper surface of a circuit board, within which a plurality of light emitting elements are positioned, which are sealed from above by a light permeable resin. A heat-dissipating heat sink is provided on a lower surface of the circuit board to protrude from the lower surface.

**1 Claim, 6 Drawing Sheets**

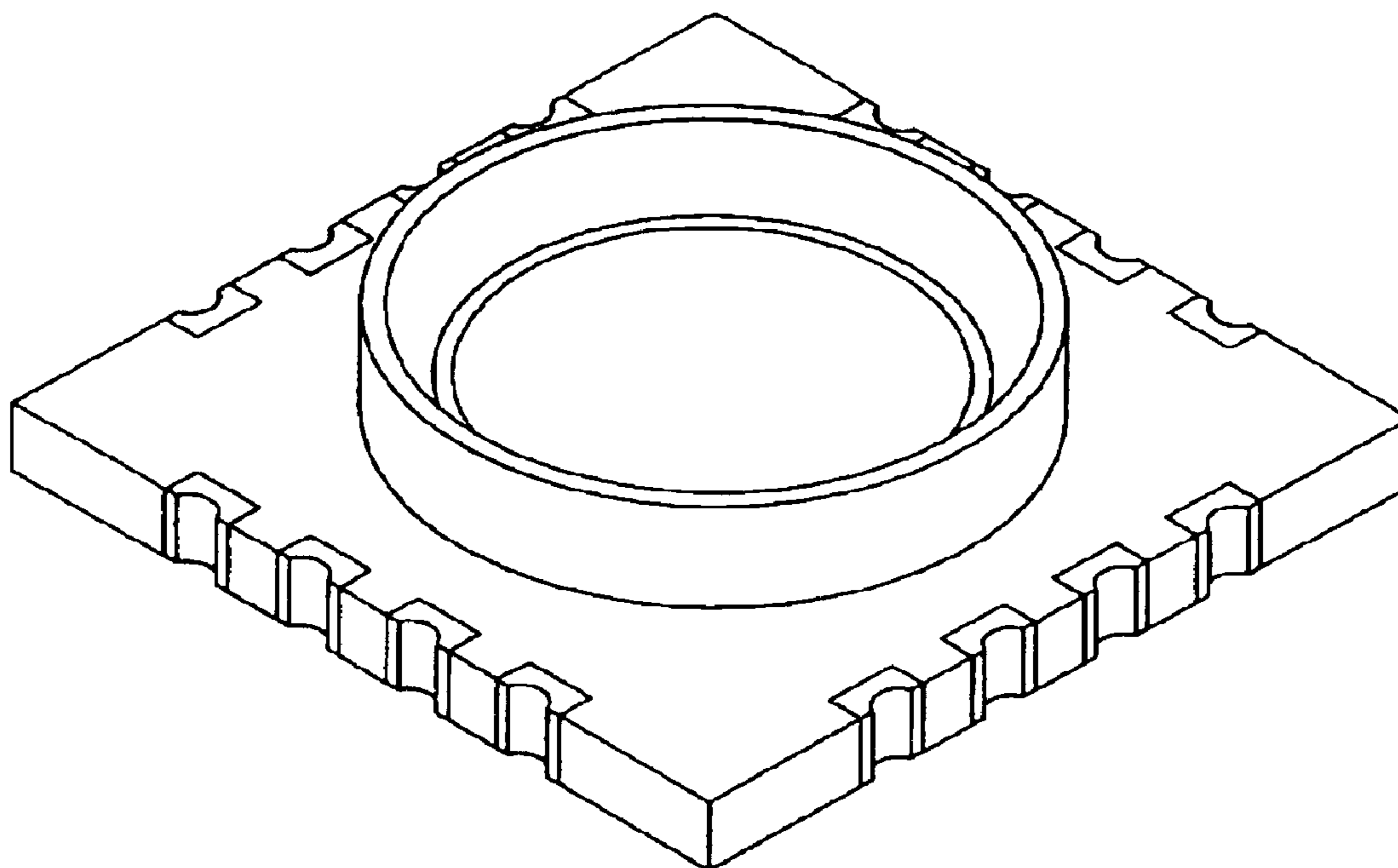


Fig. 1

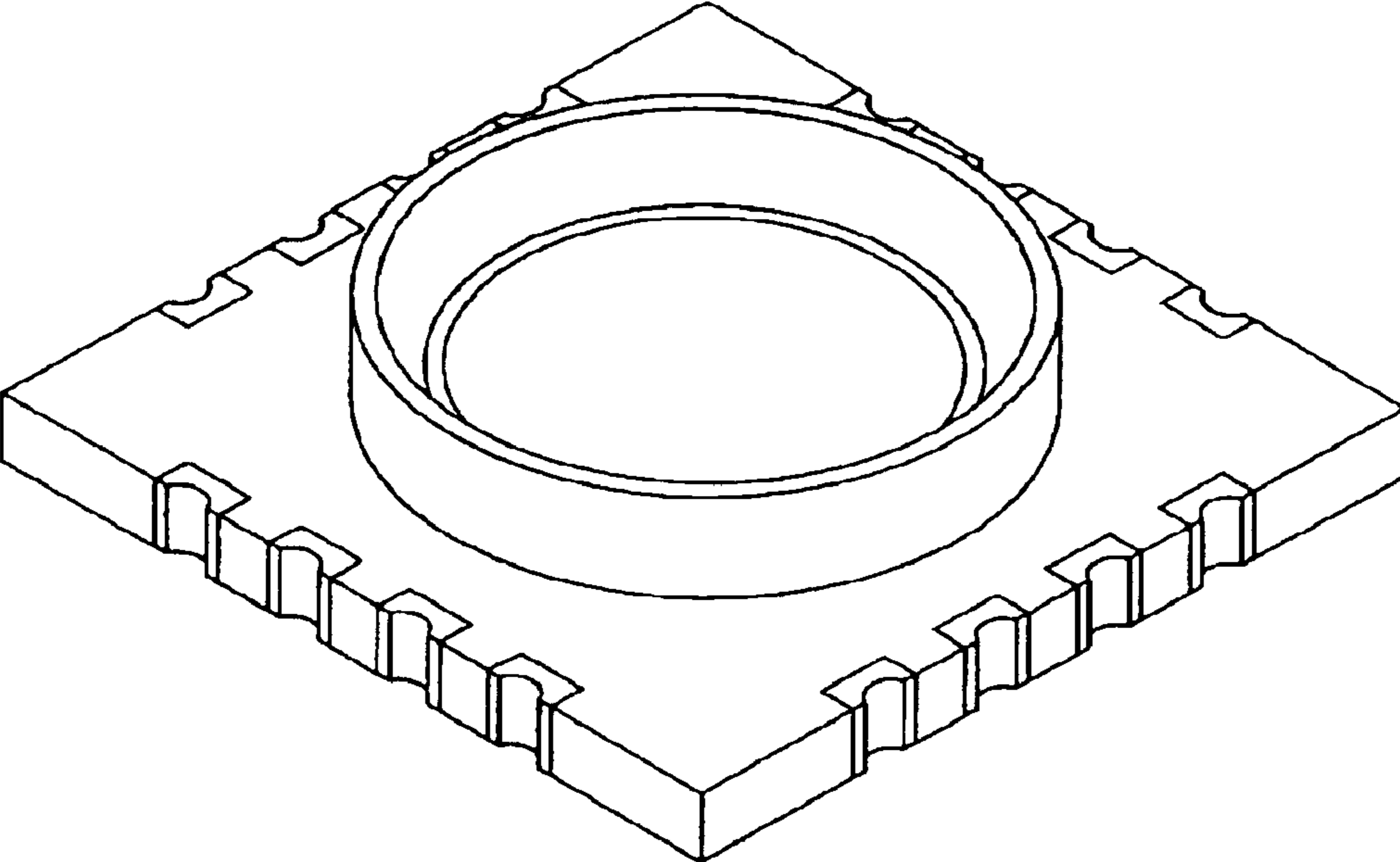
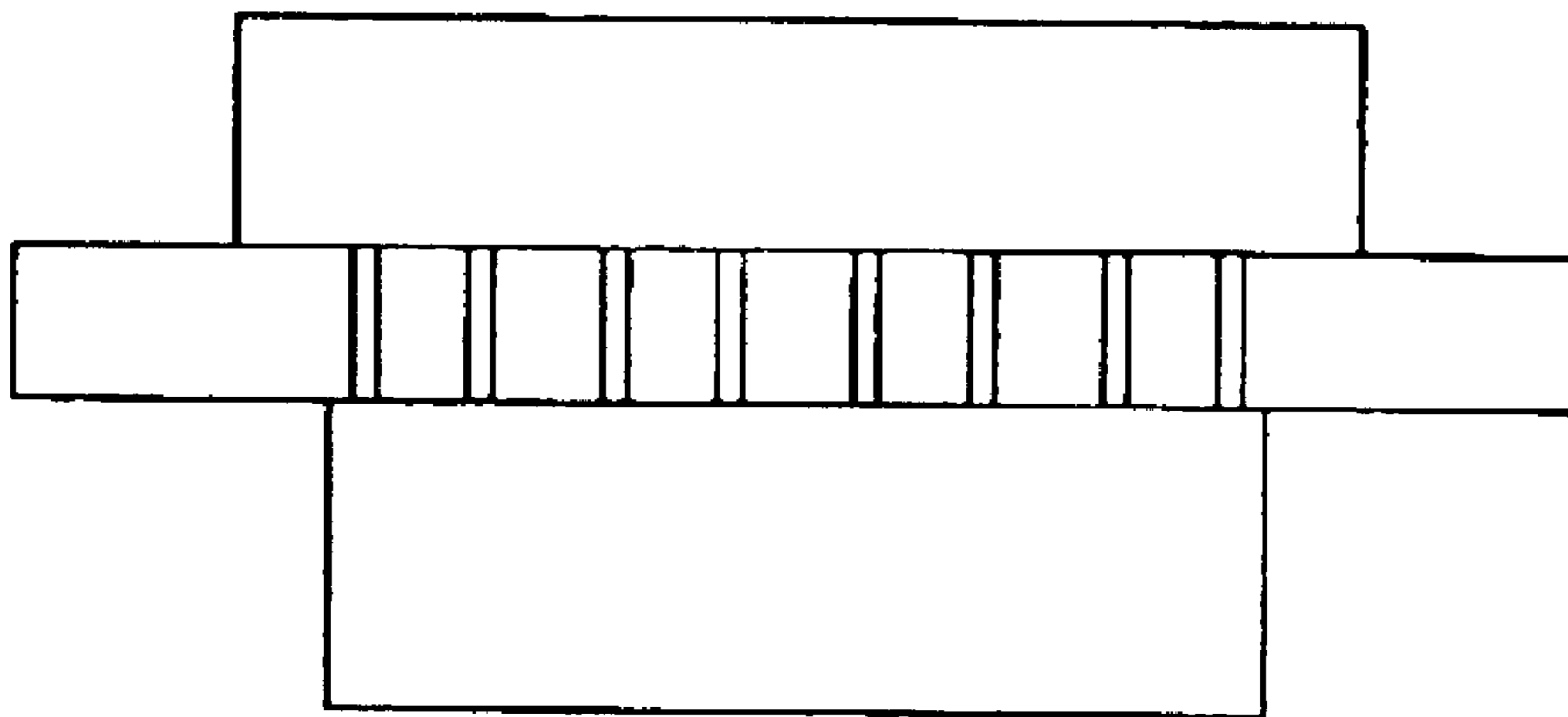


Fig. 2



# Fig. 3

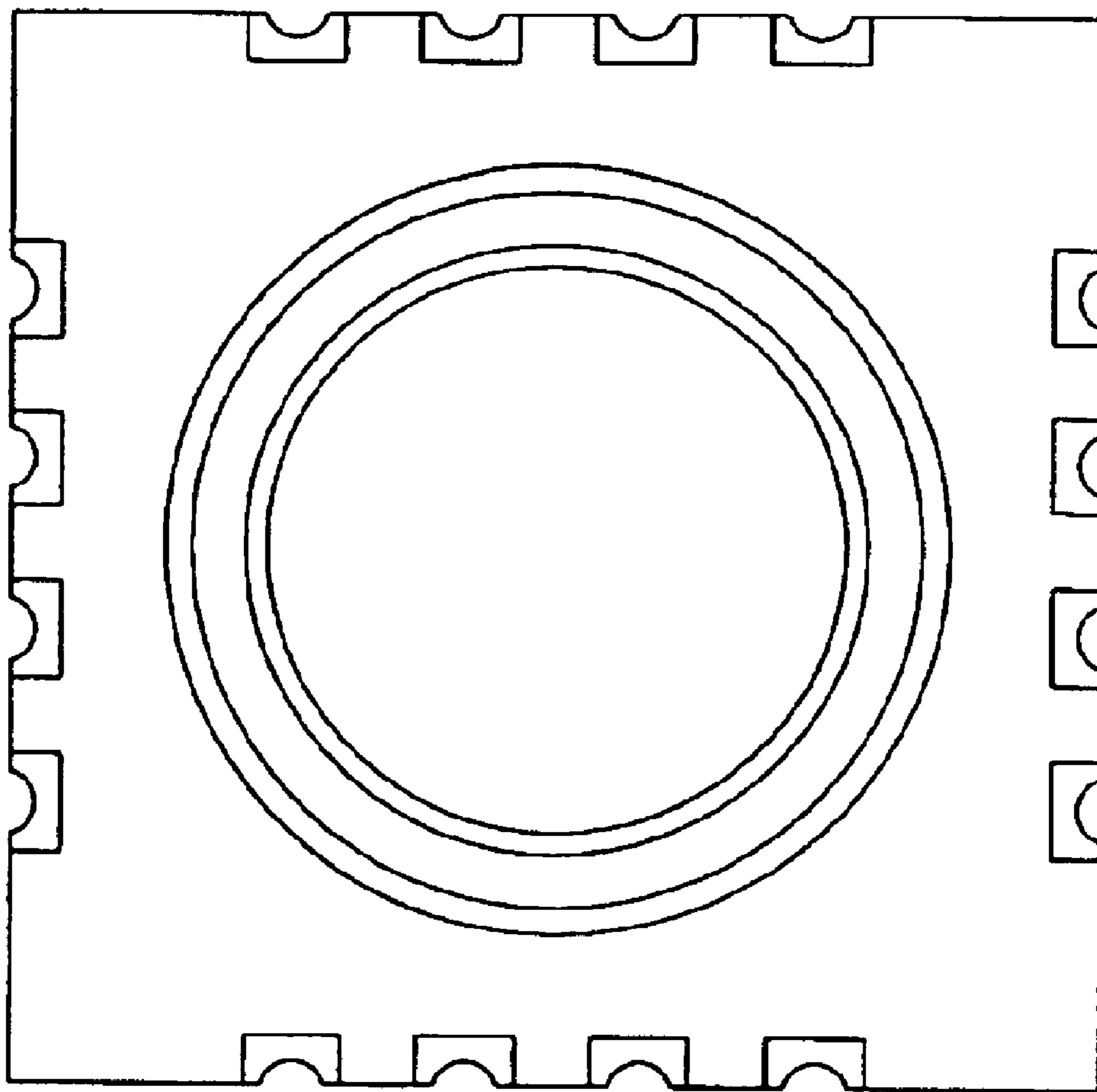


Fig. 4

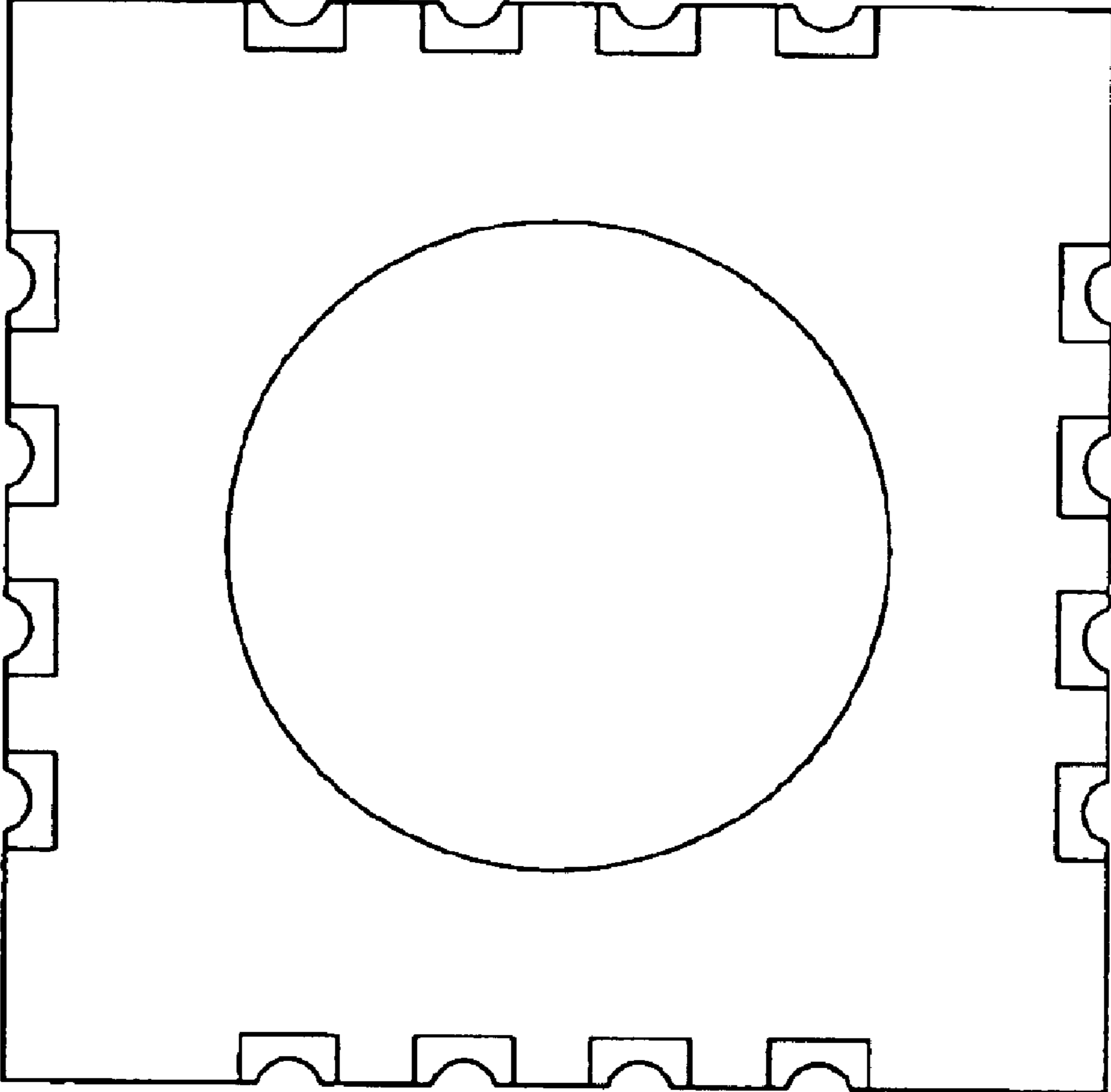


Fig. 5

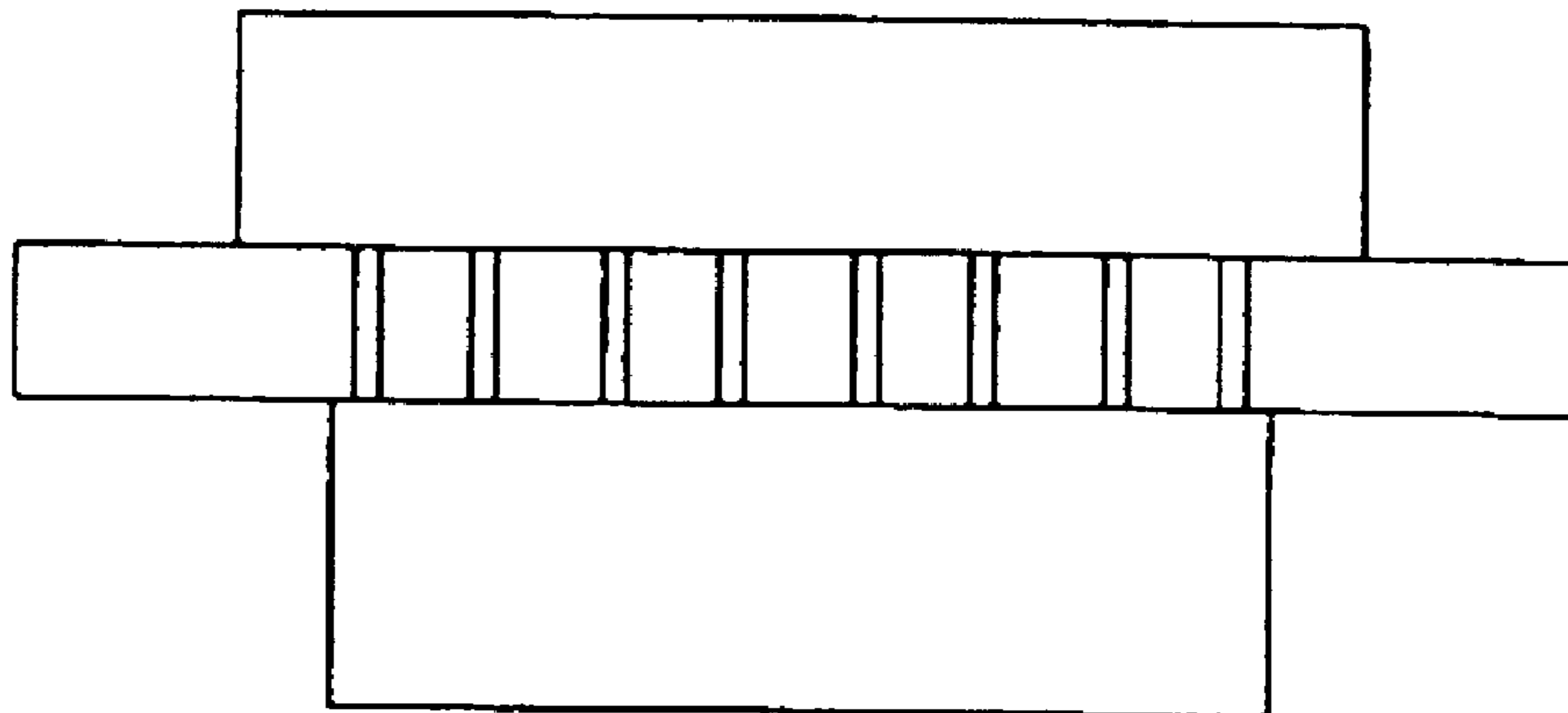


Fig. 6

